



## Material Content Data Sheet



<b>Sales Product Name</b>				IPD90N08S4-05		<b>Issued</b>		25. January 2018	
<b>MA#</b>				MA001610658					
<b>Package</b>				PG-TO252-3-313		<b>Weight*</b>		319.86 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.426	1.38	1.38	13838	13838	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		460		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		138		
	non noble metal	copper	7440-50-8	147.096	45.98	46.04	459881	460479	
wire	non noble metal	aluminium	7429-90-5	4.210	1.32	1.32	13164	13164	
encapsulation	organic material	carbon black	1333-86-4	1.361	0.43		4256		
	plastics	epoxy resin	-	23.824	7.45		74485		
	inorganic material	silicondioxide	60676-86-0	110.954	34.69	42.57	346886	425627	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11693	11693	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4441	4452	
solder	noble metal	silver	7440-22-4	0.086	0.03		268		
	non noble metal	tin	7440-31-5	0.069	0.02		214		
	non noble metal	lead	7439-92-1	3.272	1.02	1.07	10231	10713	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.00	6.01	59956	60034	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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